ASDCIATION CONNECTING ELECTRONICS INDUSTRIES® INCLUSTRIES	PC. Bannockl	burn. Illinois. A	ll rights reserved untions.	under both	This docum level parts, t	ent is a declara the declaration	ion of the s encompasse	ubstances es all lowe	within the n r level mater	nanufacture rials for wh	er listed iter hich the mar	n. Note: nufacture	if the item is an as r has engineering	sembly with lowe responsibility.
	IPC Web Site for Information on IPC-1752 Standard Form http://www.ipc.org/IPC-175x Distribution				 Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and 					lls and Mfg	and Mfg Information			
Supplier Information														
Company name* Co			Company unique ID			Unique ID Authority					Response Date*			
isemi											2024-05-18			
Contact Name	act Name Title - Contact			Phone - Contact*					Email - Contact*					
Product-Env-Stewards Product Er			Enviro Compliance			NA				Product-Env-Stewards@onsemi.com				
Authorized Representative* Title - Repre			sentative			Phone - Representative*				Email - Representative*				
Product-Env-Stewards Product			duct Enviro Compliance			NA				Product-Env-Stewards@onsemi.com				
Requester Item Number	Mfr Iten	n Number	Mfr Item Name			Effective Dat	ate Version Manufacturing Site		ng Site	We	eight*	UOM	Unit Type	
	SURA82	240T3G-GA01	REC SMA 2A 400V ULTFST TR		R	2024-05-18		(CNP		62.	01	mg	Each
Manufacturing Proccess Informa	tion		·										·	
Terminal Plating / Grid Array Ma	y Material Terminal Base		Alloy	J-STD-020 MSL Rating		Peak Pro	k Process Body Temperatur		are Max Time at Peak Tempera		Temperatur	e Num	ber of Reflow Cyc	les
Matte Tin (Sn) - annealed CU Alloy		CU Alloy		1		260		С	30		seconds	3		
omments														
vel 1 - maximum time at peak temperatu	ire during so	ldering is 10-3	0 seconds											
or more information regarding material	composition	please refer to	page 3											

RoHS Material Composition Declar	ation			Declaration Type *	Detailed
Directive 2015/863/EU amending Rol Directive 2011/65/EU	(Pb), Mercury (Hg), Hexav		ninated Biphenyls (PBB), Polybror	dmium and quantity limit of 0.1% by mass (100 ninated Diphenyl Ethers (PBDE), and Bis(2-eth	
cadmium, hexavalentchromium, polyb contains a RoHS restricted substance i encompass all such components.Suppl as of the date that Supplier completes Company acknowledges that Supplier independently verified information pro- certification in this paragraph.If the Co	rominated biphenyls and/or polybror nexcess of an applicable quantity lim ier certifies that it gathered the inforr this form.Supplier acknowledges that may have relied on informationprovi ovided by others, Supplier agrees that ompany and the Supplier enter into a clusivesource of the Supplier's liabili	ninated diphenyl ethers (each a "R it, please indicate below which, if nation it provides in this form usin Company will rely on this certifud ded by others in completing this f , at a minimum, itssuppliers have written agreement with respect to ty and the Company's remedies for	toHS restricted substance") in exce any, RoHS exemption you believe ag appropriate methods to ensure it cation in determining the complian orm, and that Supplier may not hav provided certifications regarding th the identified part,the terms and co or issues that arise regarding inform	ropean Union member states) of the part identifies so of the applicable quantity limit identified about may apply. If the part is an assembly with lows a accuracy and that such information is true and ce of its products with European Union member re independently verified such information. How heir contributions to the part, and those certifica motions of that agreement, including any warra nation the Supplier provides in this form. In the	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the inty rights and/or remedies provided as part of
RoHS Declaration * 4	- Item(s) does not contain RoHS restr	icted substances per the definition	above except for selected exempti	ons Supplier Acceptance	* Accepted
Exemption: 7a: Lead in high meltin Exemption: 7c-I Electrical and elect	g temperature type solders (i.e. lead ronic components containing lead i	l based solder alloys containing n a glass or ceramic other than	85% by weight or more lead). dielectric ceramic in capacitors, o	e.g. piezoelectronic devices, or in a glass or ce	eramic matrix compound.
Exemption List Version	EL-2011/534/EU				
Declaration Signature					
Instructions: Complete all of the rec Requester) and click on Submit For			Supplier Acceptance drop-down	. This will display the signature area. Digital	ly sign the declaration (if required by the
Supplier Digital Signature	Rastislav Drska	Le			

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Clip	6.0	mg	Supplier	Iron (Fe)	7439-89-6		0.006	mg
			Supplier	Copper (Cu)	7440-50-8		5.9922	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0018	mg
Die	0.84	mg	Supplier	Silicon (Si)	7440-21-3		0.785	mg
			В	Nickel (Ni)	7440-02-0		0.0097	mg
			Supplier	Lead Bisilicate	65997-18-4	7c	0.0454	mg
Die Attach Solder	2.92	mg	Supplier	Silver (Ag)	7440-22-4		0.073	mg
			А	Lead (Pb)	7439-92-1	7a	2.701	mg
			Supplier	Tin (Sn)	7440-31-5		0.146	mg
Lead Frame	22.63	mg	Supplier	Iron (Fe)	7439-89-6		0.0226	mg
			Supplier	Copper (Cu)	7440-50-8		22.6006	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0068	mg
Mold Compound-Black	29.54	mg	Supplier	Polycondensate of 4,4'- bis(methoxymethyl)biphenyl and phenol	205830-20-2		0.7385	mg
			Supplier	Triphenylphosphine	603-35-0		0.1477	mg
			Supplier	Trimethoxysilylpropanethiol	4420-74-0		0.1477	mg
			Supplier	4,4'-Bis(2,3-epoxypropoxy)-3,3',5,5'- tetramethylbiphenyl	85954-11-6		0.1477	mg
			Supplier	Carbon Black (C)	1333-86-4		0.2954	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		26.586	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		1.477	mg
Plating	0.08	mg	Supplier	Tin (Sn)	7440-31-5		0.08	mg